

**ELECTRONIC PACKAGE HAVING CONTROLLED
HEIGHT STAND-OFF SOLDER JOINT**

Abstract of the Disclosure

5 An electronic package (10) is provided which includes a circuit board (12) having a substrate (14) and circuitry (16) and a surface mount device (22) having a contact terminal (24). A mounting pad (28) is formed on the circuit board (12). The electronic package (10) also includes a solder joint (30) connecting the contact terminal (24) of the surface mount device (22) to
10 the mounting pad (28) on the circuit board (12). The solder joint (30) includes a reflowable solder and a plurality of stand-off members (32 or 42). The stand-off members (32 or 42) provide a separation distance (H) between the circuit board (12) and surface mount device (22) in the range of about 0.01 mm to 0.10 mm.

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